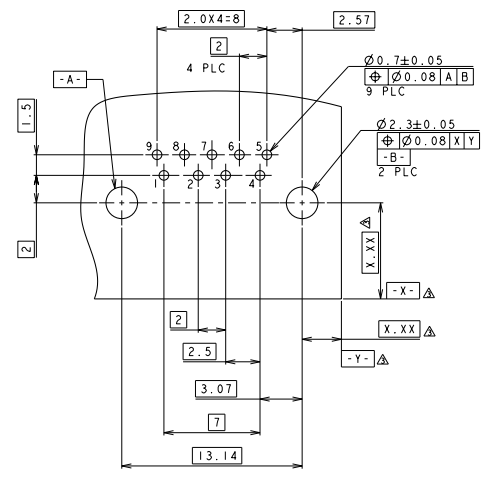
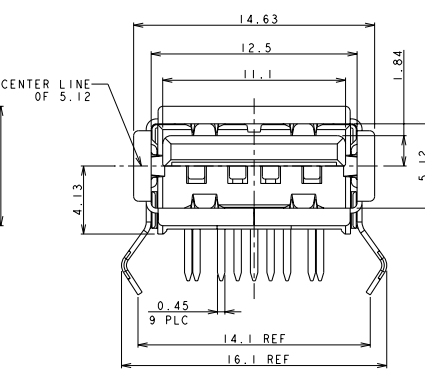
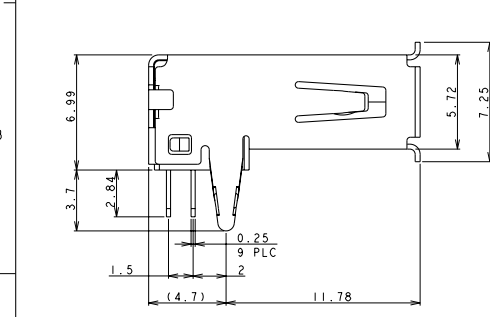
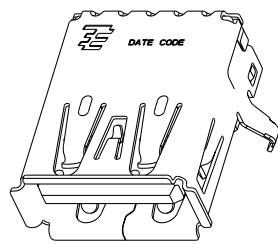
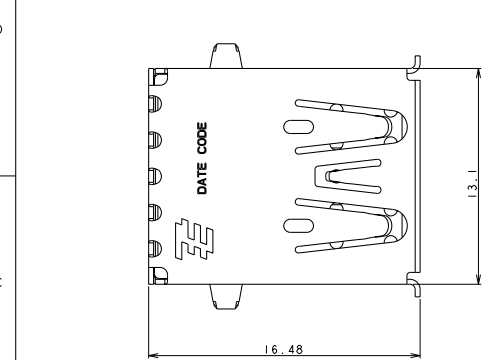


LOC	DISP	REV	DESCRIPTION	DATE	BY	APPD
ES	00					
		A2	REVISED PER ECO-11-005033	16APR2011	RK	HMR



RECOMMENDED PCB LAYOUT (CONNECTOR MOUNTING SIDE VIEW)

NOTE:  
 MATERIAL: SHELL AND CONTACTS: COPPER ALLOY  
 HOUSING: THERMOPLASTIC, BLUE  
 PLATING: CONTACT: 0.76um MIN GOLD OR GOLD FLASHED OVER 0.76um MIN Pd-Ni ON MATING AREA, 2.54um MIN MATTE TIN ON SOLDER TAILS, 1.2um MIN NICKEL UNDER PLATING  
 SHELL: TIN OVER NICKEL PLATING  
 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PC BOARD THICKNESS OF 1.60  
 PIN ASSIGNMENT:

PIN NO.	1	2	3	4	5	6	7	8	9
SIGNAL NAME	VBUS	D-	D+	GND	STDA_SSRX*	STDA_SSRX*	STDA_SSRX*	STDA_SSRX*	STDA_SSRX*
REMARK	USB 2.0 CONTACT PIN				USB 3.0 CONTACT PIN				

P/N: 1932258-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 13SEP2010		REV: 1		TE Connectivity	
DRAWN BY: J. FRANCKIS		CHKD BY: MARTIN LI		APPD BY: STEVEN YAO		NAME	
DIMENSIONS: mm		PRODUCT SPEC: 108-115001		APPLICATION SPEC: 501-115002		SHEET CASE CODE DRAWING NO. A200779	
MATERIAL: THERMOPLASTIC		WEIGHT: -		SCALE: NTS		RESTRICTED TO: -	
CUSTOMER DRAWING		SCALE: NTS		SHEET 1 OF 1		REV A2	